

N-Channel Power MOSFET (8A, 600Volts)

DESCRIPTION

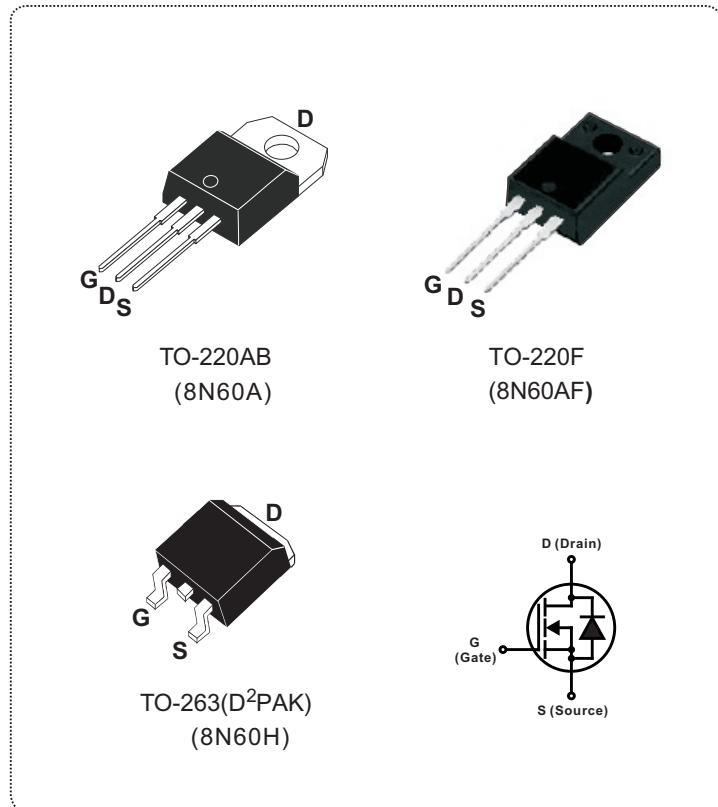
The Nell **8N60** is a three-terminal silicon device with current conduction capability of 8A, fast switching speed, low on-state resistance, breakdown voltage rating of 600V ,and max. threshold voltage of 4 volts.

They are designed for use in applications. such as switched mode power supplies, DC to DC converters, **PWM** motor controls, bridge circuits, and general purpose switching applications .

FEATURES

- $R_{DS(ON)} = 1.2\Omega @ V_{GS} = 10V$
- Ultra low gate charge(36nC max.)
- Low reverse transfer capacitance ($C_{RSS} = 12pF$ typical)
- Fast switching capability
- 100% avalanche energy specified
- Improved dv/dt capability
- 150°C operation temperature

PRODUCT SUMMARY	
I _D (A)	8
V _{DSS} (V)	600
R _{DS(ON)} (Ω)	1.2 @ V _{GS} = 10V
Q _G (nC) max.	36



ABSOLUTE MAXIMUM RATINGS (T_C = 25°C unless otherwise specified)

SYMBOL	PARAMETER	TEST CONDITIONS		VALUE	UNIT
V _{DSS}	Drain to Source voltage	T _J =25°C to 150°C		600	V
V _{DGR}	Drain to Gate voltage	R _{GS} =20K Ω		600	
V _{GS}	Gate to Source voltage			± 30	
I _D	Continuous Drain Current	T _C =25°C		8	A
		T _C =100°C		5	
I _{DM}	Pulsed Drain current(Note 1)			32	
I _{AR}	Avalanche current(Note 1)			8	
E _{AR}	Repetitive avalanche energy(Note 1)	I _{AR} =8A, R _{GS} =50 Ω , V _{GS} =10V		14.7	mJ
E _{AS}	Single pulse avalanche energy(Note 2)	I _{AS} =8A, L=7.1mH		230	
dv/dt	Peak diode recovery dv/dt(Note 3)			4.5	V /ns
P _D	Total power dissipation	T _C =25°C	TO-220AB/TO-263	150	W
			TO-220F	48	
T _J	Operation junction temperature			-55 to 150	°C
T _{STG}	Storage temperature			-55 to 150	
T _L	Maximum soldering temperature, for 10 seconds	1.6mm from case		300	
	Mounting torque, #6-32 or M3 screw			10 (1.1)	lbf-in (N·m)

Note: 1.Repetitive rating: pulse width limited by junction temperature..

2.I_{AS} = 8A, V_{DD} = 50V, L = 7.1mH, R_{GS} = 25 Ω , starting T_J=25°C.

3.I_{SD} \leq 7.5A, di/dt \leq 200A/ μ s, V_{DD} \leq V_{(BR)DSS}, starting T_J=25°C.

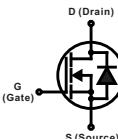
THERMAL RESISTANCE						
SYMBOL	PARAMETER		Min.	Typ.	Max.	UNIT
$R_{th(j-c)}$	Thermal resistance, junction to case	TO-220AB/TO-263			0.85	$^{\circ}\text{C}/\text{W}$
		TO-220F			2.6	
$R_{th(j-a)}$	Thermal resistance, junction to ambient	TO-220AB/TO-263			62.5	$^{\circ}\text{C}/\text{W}$
		TO-220F			62.5	

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}\text{C}$ unless otherwise specified)						
SYMBOL	PARAMETER	TEST CONDITIONS	Min.	Typ.	Max.	UNIT
$V_{(BR)DSS}$	Drain to source breakdown voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	600			V
$\Delta V_{(BR)DSS}/\Delta T_J$	Breakdown voltage temperature coefficient	$I_D = 250\mu\text{A}, V_{DS}=V_{GS}$		0.7		$\text{V}/^{\circ}\text{C}$
I_{DSS}	Drain to source leakage current	$V_{DS}=600\text{V}, V_{GS}=0\text{V}$	$T_C = 25^{\circ}\text{C}$		10	μA
		$V_{DS}=480\text{V}, V_{GS}=0\text{V}$	$T_C=125^{\circ}\text{C}$		100	
I_{GSS}	Gate to source forward leakage current	$V_{GS} = 30\text{V}, V_{DS} = 0\text{V}$			100	nA
	Gate to source reverse leakage current	$V_{GS} = -30\text{V}, V_{DS} = 0\text{V}$			-100	
$R_{DS(\text{ON})}$	Static drain to source on-state resistance	$I_D = 4\text{A}, V_{GS} = 10\text{V}$		1	1.2	Ω
$V_{GS(\text{TH})}$	Gate threshold voltage	$V_{GS}=V_{DS}, I_D=250\mu\text{A}$	2		4	V
C_{ISS}	Input capacitance	$V_{DS} = 25\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		965	1255	pF
C_{OSS}	Output capacitance			105	135	
C_{RSS}	Reverse transfer capacitance			12	16	
$t_{d(\text{ON})}$	Turn-on delay time	$V_{DD} = 300\text{V}, V_{GS} = 10\text{V}, I_D = 8\text{A}, R_{GS} = 25\Omega$ (Note 1, 2)		16.5	45	ns
t_r	Rise time			60.5	130	
$t_{d(\text{OFF})}$	Turn-off delay time			81	170	
t_f	Fall time			64.5	140	
Q_G	Total gate charge	$V_{DD} = 480\text{V}, V_{GS} = 10\text{V}, I_D = 8\text{A}$ (Note 1, 2)		28	36	nC
Q_{GS}	Gate to source charge			4.5		
Q_{GD}	Gate to drain charge (Miller charge)			12		

SOURCE TO DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_C = 25^{\circ}\text{C}$ unless otherwise specified)						
SYMBOL	PARAMETER	TEST CONDITIONS	Min.	Typ.	Max.	UNIT
V_{SD}	Diode forward voltage	$I_{SD} = 8\text{A}, V_{GS} = 0\text{V}$			1.4	V
$I_s (I_{SD})$	Continuous source to drain current	Integral reverse P-N junction diode in the MOSFET			8	A
I_{SM}	Pulsed source current				32	
t_{rr}	Reverse recovery time	$I_{SD} = 8\text{A}, V_{GS} = 0\text{V}, dI_F/dt = 100\text{A}/\mu\text{s}$		320		ns
Q_{rr}	Reverse recovery charge			2.4		

Note: 1. Pulse test: Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

2. Essentially independent of operating temperature.



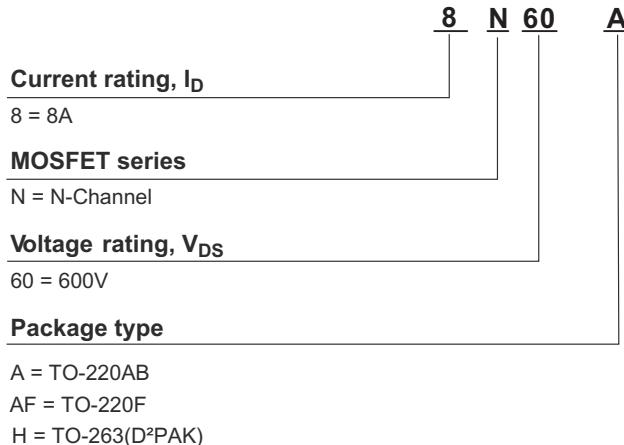
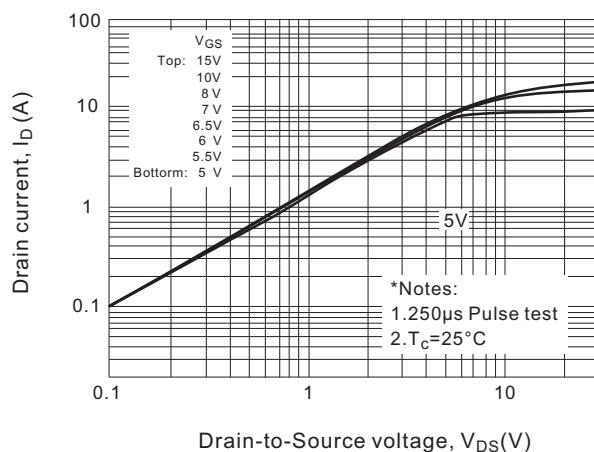
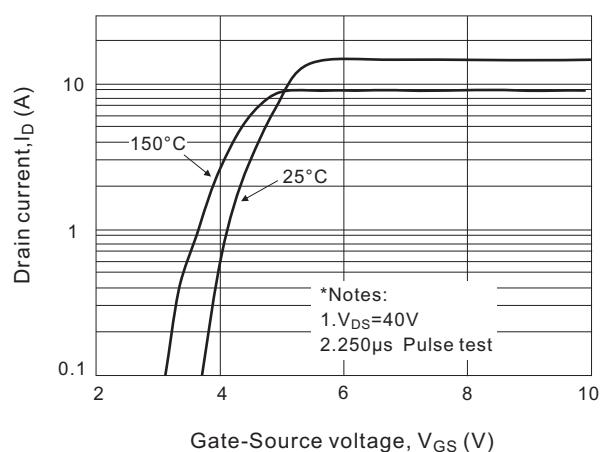
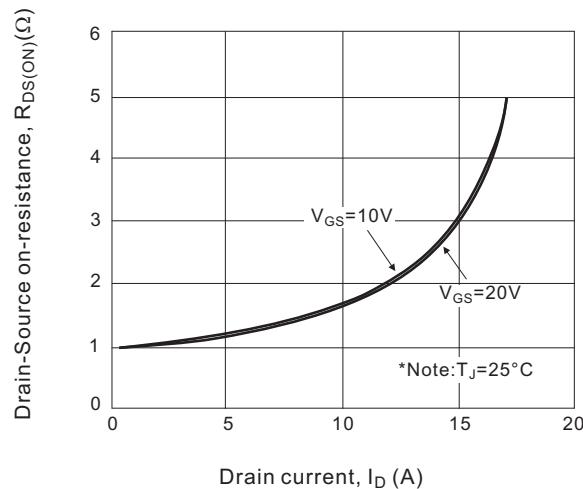
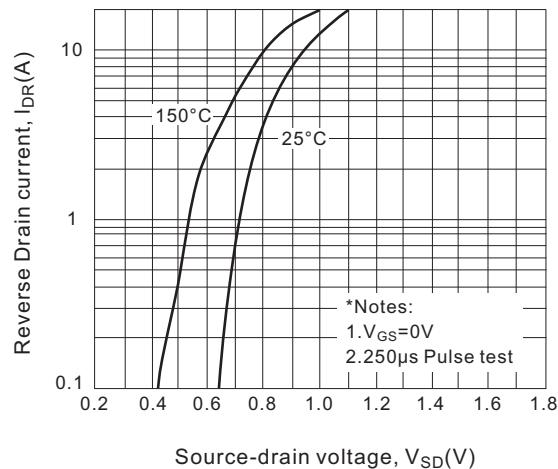
ORDERING INFORMATION SCHEME

Fig.1 On-State characteristics

Fig.2 Transfer characteristics

Fig.3 On-resistance variation vs. drain current and gate voltage

Fig.4 Body diode forward voltage vs. source current


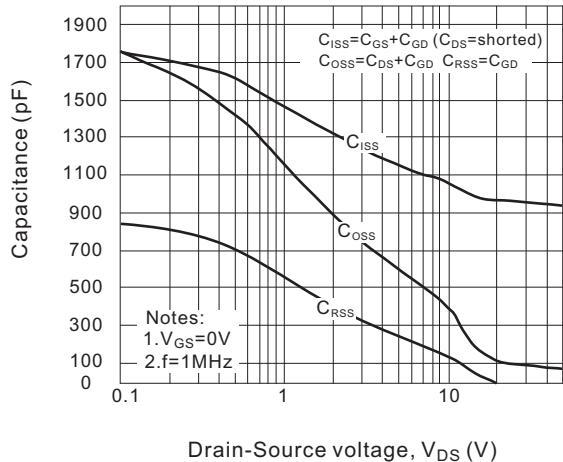
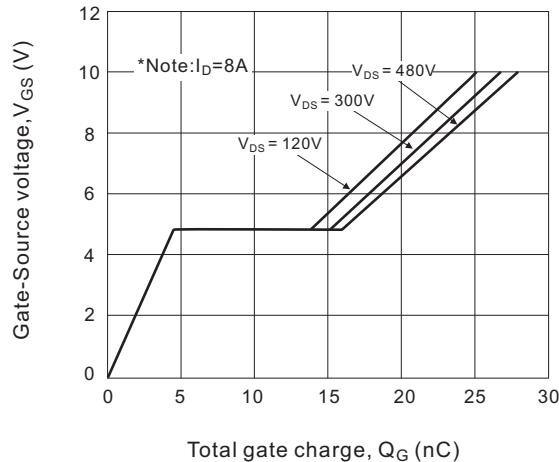
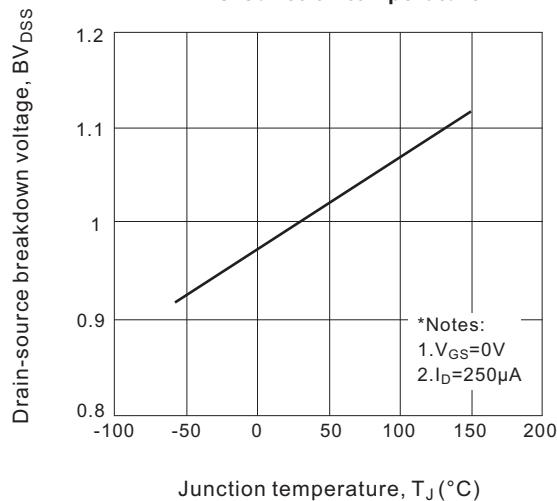
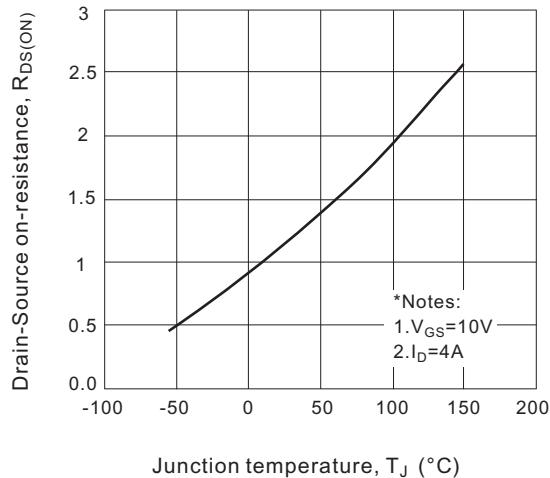
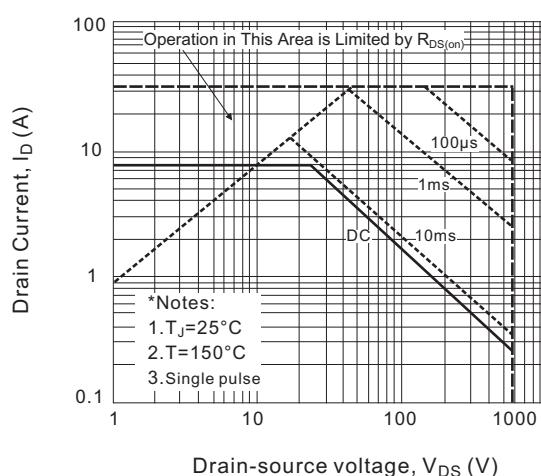
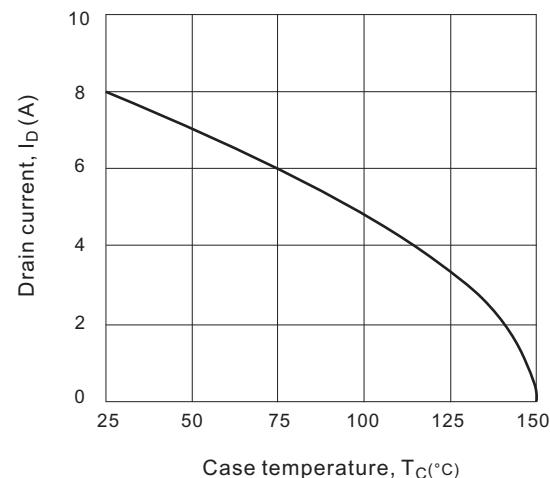
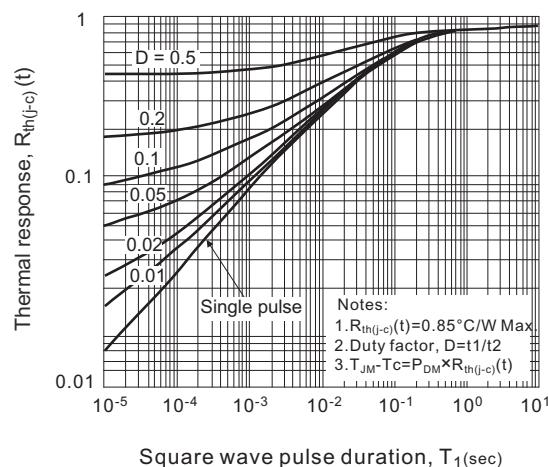
Fig.5 Capacitance characteristics

Fig.6 Gate charge characteristics

Fig.7 Breakdown voltage variation vs. Junction temperature

Fig.8 On-resistance Junction temperature

Fig.9 Maximum safe operating area

Fig.10 Maximum drain current vs. case temperature


Fig.11 Transient thermal response curve


■ TEST CIRCUITS AND WAVEFORMS

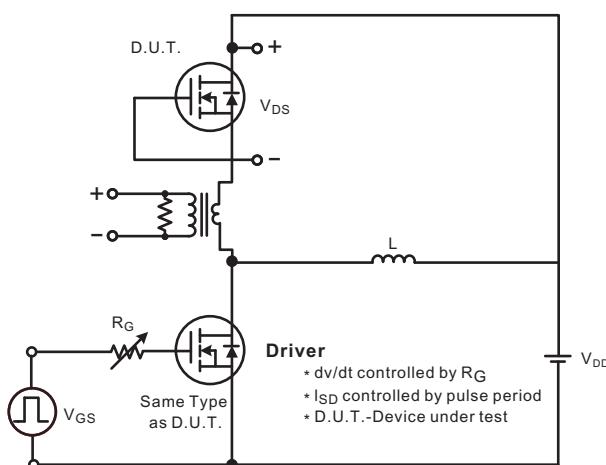
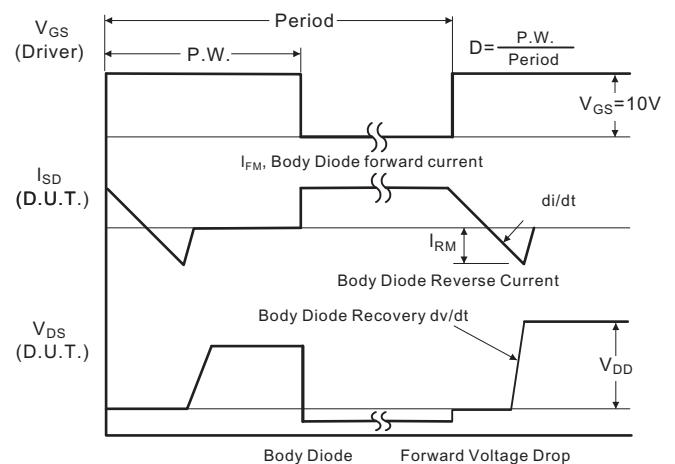
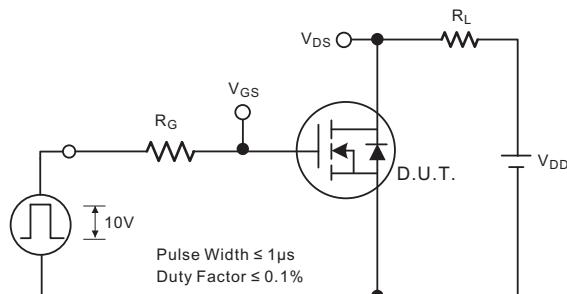
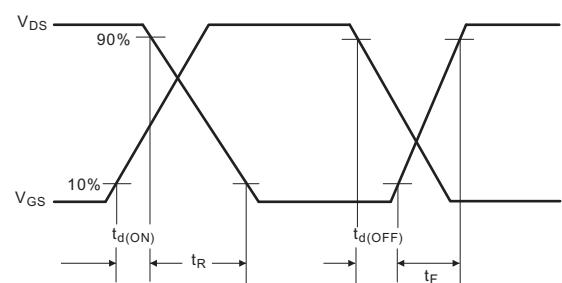
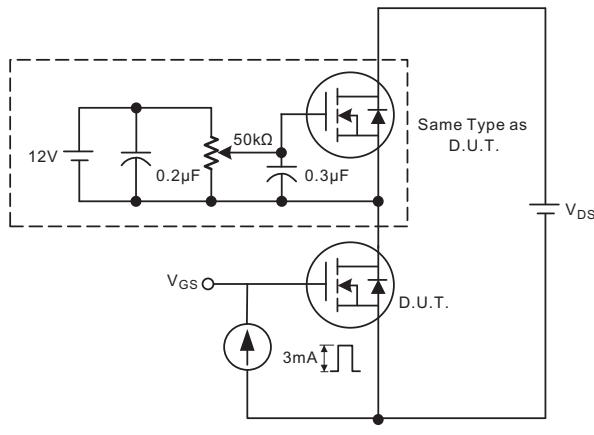
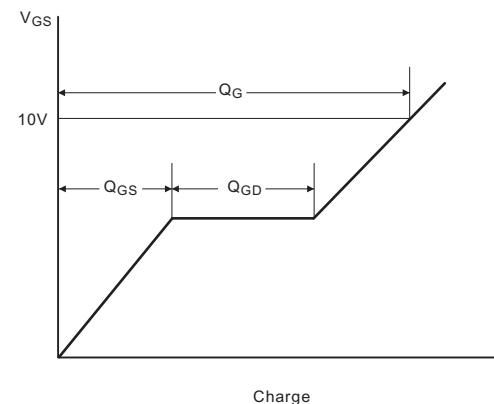
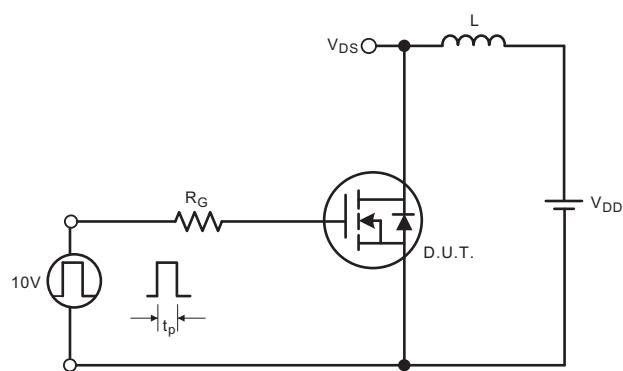
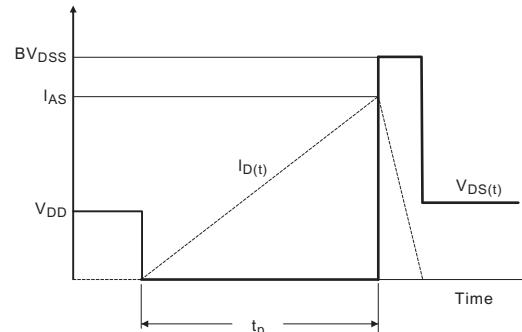
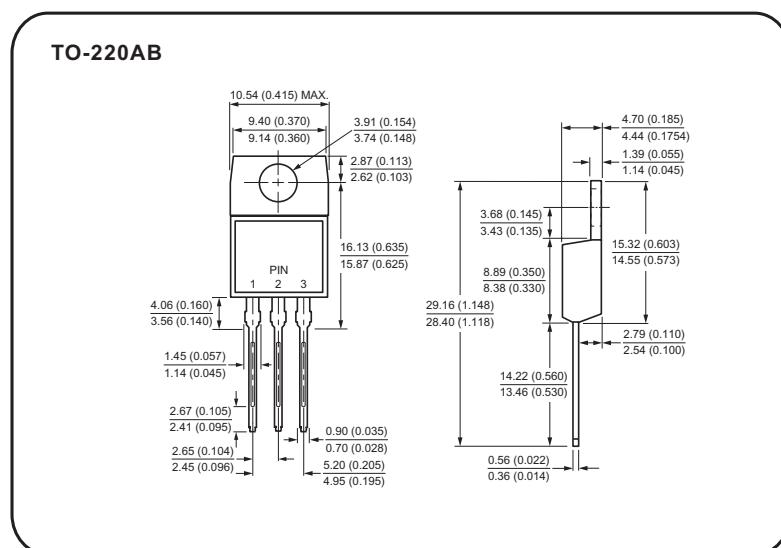
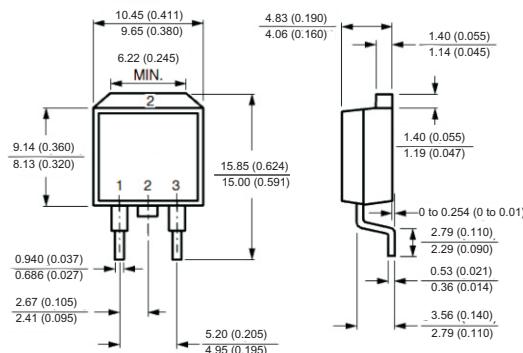
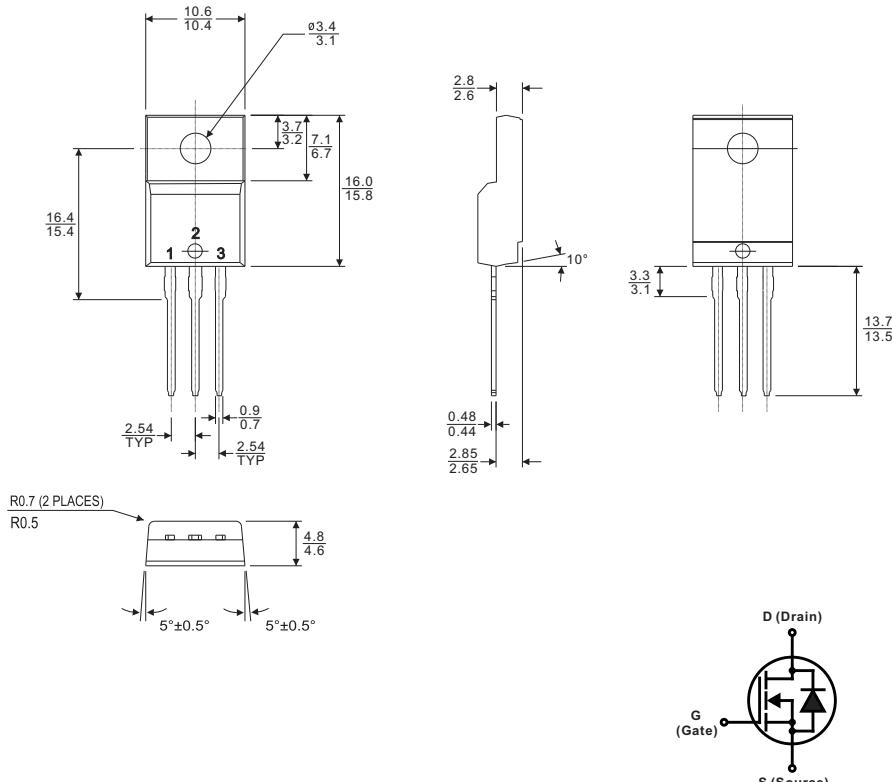
Fig.1A Peak diode recovery dv/dt test circuit

Fig.1B Peak diode recovery dv/dt waveforms

Fig.2A Switching test circuit

Fig.2B Switching Waveforms


Fig.3A Gate charge test circuit

Fig.3B Gate charge waveform

Fig.4A Unclamped Inductive switching test circuit

Fig.4B Unclamped Inductive switching waveforms


Case Style



Case Style

TO-263(D²PAK)

TO-220F


All dimensions in millimeters